

## REMARKS

Favorable reconsideration is respectfully requested.

Upon entry of the above amendment, the claims will be 1, 3, 4, and 8 to 13.

The above amendment is responsive to points set forth in the Official Action.

In this regard, the features of claims 2, 5 and 6 have been incorporated into claim 1.

Further, claim 4 has been divided into two claims, i.e. amended claim 4 and new claim 13.

The significance of these amendments will become further apparent from the remarks below.

Claims 2 to 5 and 7 to 12 have been rejected under 35 U.S.C. 103(a) as being unpatentable over JP 6319114 or EP 118031 in view of Nakamura ('630).

This rejection is respectfully traversed.

The Official Action states that claim 6 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. See Official Action at page 4, lines 10 to 12. The Official Action further states that Applicants' claims allow for even tiny amounts of boehmite in the aluminum hydroxide.

In accordance with the above comments, claim 1 is amended to incorporate the features of claims 2, 5 and 6. Since all claims contain the feature of allowable claim 6, all claims are considered to be allowable as explained in detail below.

JP 63195114 ('114, hereinafter) provides a gibbsite type aluminum hydroxide which contains substantially no boehmite type aluminum hydroxide by hydrothermally treating a gibbsite type aluminum at 50 to 200°C, preferably 10 to 180°C.

On the other hand, the present invention provides a prepreg for a printed wiring board material. Inorganic fillers used in the prepreg are the aluminum hydroxide-boehmite composite (A) obtained by hydrothermal treatment of aluminum hydroxide and the boehmite (B) and the present invention is characterized in that the aluminum hydroxide-boehmite composite (A) and the boehmite (B) are used in a specific ratio and that aluminum hydroxide and boehmite in the composite (A) are contained in a specific ratio.

It is apparent that '114 does not at all teach or suggest the above concepts.

EP 118031 ('031, hereinafter) discloses, as filler, a hydrargillite type aluminum in which the surface of the crystallites is dehydrated.

On the other hand, aluminum hydroxide-boehmite composite (A) and the boehmite (B) are contained in the thermosetting resin composition (D) of the present invention, and the present invention is characterized in that the composite (A) and the boehmite (B) are present in a specific ratio.

It is clear that '031 also does not teach or suggest the present invention.

Nakamura (U.S. 6,645,630) discloses an epoxy resin composition comprising a phosphorus compound, aluminum hydroxide and a bifunctional epoxy resin.

On the other hand, the prepreg of the present invention does not use a phosphorus compound as an essential component. The prepreg of the present invention uses the boehmite type aluminum hydroxide which overcomes the insufficient heat resistance problem of general aluminum hydroxide and it also contains boehmite as an essential component.

It is clear that Nakamura ('630) does not overcome the above-discussed deficiencies of the primary references.

Claims 1 to 3 and 8 to 12 have been rejected under 35 U.S.C. 102(b) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over Brown WO 98/31538.

This rejection is also respectfully traversed.

WO 98/31538, '538, hereinafter) discloses laminate for printed circuit boards, comprising in intermediate layers a predetermined amount of thermally stable aluminum hydroxide of which the boehmite ratio is relatively lower in comparison with that of general heat-treated aluminum hydroxide.

On the other hand, the present invention provides a prepreg for a printed wiring board, using as inorganic fillers an aluminum hydroxide-boehmite composite (A), of which the boehmite ratio is relatively high in comparison with that of general heat-treated aluminum hydroxide, and boehmite (B).

It is clear that the present claims are unobvious from '538.

Claims 1 to 5 and 7 to 12 are rejected under 35 U.S.C. 102(e) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over Nakamura ('630).

This rejection is also respectfully traversed.

The deficiencies of Nakamura ('630) are discussed above and are incorporated by reference here. It is clear that Nakamura ('630) does not teach or suggest the present claims.

Claims 1 to 3, 5 and 7 to 12 rejected under 35 U.S.C. 102(a,b) as anticipated by, or in the alternative, under 35 U.S.C. 103(a) as obvious over JP 2001-329080.

This rejection is respectfully traversed.

JP 2001-329080 ('080, hereinafter) discloses a prepreg as a printed wiring board material which prepreg uses a specific glass cloth as a reinforcing material of a thermosetting resin composition. Further, '080 discloses that general aluminum hydroxide is used as an inorganic filler in the thermosetting resin composition.

On the other hand, the prepreg of the present invention contains, as inorganic filler, the boehmite type aluminum hydroxide and boehmite as essential components. It is clear that '080 does not teach or suggest the present claims.

None of the above cited references teach the advantageous combined use of boehmite as inorganic filler and the mixing ratio thereof. See e.g. paragraphs [0011] to [0013] of the present specification in this regard.

No further issues remaining, allowance of this application is respectfully requested.

If the Examiner has any comments or proposals for expediting prosecution, please contact undersigned at the telephone number below.

Respectfully submitted,

Hiroyuki MISHIMA et al.

By: 

Matthew M. Jacob  
Registration No. 25,154  
Attorney for Applicants

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MJ/kes  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
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